

IN THE CLAIMS:

1 1. (Currently Amended) A multilayer board on whose outside layer, one or more
2 circuit components are mounted, the multilayer board comprising:

3 a signal line requiring tamper-resistance, the signal line being connected to a
4 predetermined component among the one or more circuit components and including: (a) a
5 conductive trace and (b) a conductive via that passes through layers of the multilayer board,
6 wherein

7 the conductive trace and an end of the conductive via existing on ~~an~~ the outside
8 layer of the multilayer board are placed ~~under one or more circuit components mounted on the~~
9 ~~outside layer~~ only under the predetermined component, and not on the other area of the outside
10 layer.

1 2. (Original) The multilayer board of Claim 1, wherein

2 the signal line further includes a conductive trace on an inner layer that is
3 sandwiched between sheets of foil and/or circuit components placed on layers above and below
4 the inner layer so that the sheets of foil and/or circuit components hide the conductive trace on
5 the inner layer when viewed from above or below.

1 3. (Original) The multilayer board of Claim 2, wherein

2 the sheets of foil placed on the layers that are outside the inner layer are
3 connected to either a ground or a power source.

1 4. (Original) The multilayer board of Claim 3, wherein

2 the conductive trace on the outside layer is further covered by a circuit component
3 on another outside layer when viewed from above or below.

1 5. (Original) The multilayer board of Claim 2, wherein
2 the signal line requiring tamper-resistance is either a signal line that is input to an
3 encryption unit or a signal line that is output from a decryption unit.

1 6. (Currently Amended) A multilayer board on whose outside layer, one or more
2 circuit components are mounted, the multilayer board comprising:

3 a certain signal line that is connected to a predetermined component among the
4 one or more circuit components and includes (a) a conductive trace and (b) a conductive via that
5 passes through layers of the multilayer board, wherein

6 the conductive trace and an end of the conductive via existing on ~~an~~ the outside
7 layer of the multilayer board are placed ~~under one or more circuit components mounted on~~ only
8 under the predetermined component, and not on the other area of the outside layer,

9 the certain signal line further includes a conductive trace on an inner layer ~~that is~~
10 of the multilayer board, the conductive trace being sandwiched between sheets of foil and/ or
11 circuit components placed on layers above and below the inner layer so that the sheets of foil
12 and/or ~~circuit components~~ the predetermined component hide the conductive trace on the inner
13 layer when viewed from above or below, and

14 the certain signal line is either a data line or an address line.

1 7-29. (Cancelled)

1 30. (Currently Amended) A tamper-resistant multilayer board for transfer of pixel
2 data to be encrypted comprising:

3 a board member having a plurality of layers and one or more components
4 mounted thereon;

5 a reception/decryption unit mounted on the board member;

6 an output interface unit mounted on the board member and operatively connected
7 to the reception/decryption unit; and

8 a conductive path operatively designed for interconnecting the reception/
9 decryption unit and the output interface unit and ~~position~~ positioned adjacent an interior layer
10 surface for a portion of the conductive path and positioned under ~~one or more components~~ the
11 reception/decryption unit and/or the output interface unit only for the remainder of the
12 conductive path to prevent direct access from the exterior of the board member.